**Amendments to the Claims**:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A fluid ejector carriage assembly, comprising:

a thermally-conductive fluid ejector carriage device; and

a fluid ejector module in thermal contact with the thermally-conductive fluid ejector carriage device,

wherein the thermally-conductive fluid ejector carriage device ~~is molded from~~ consists essentially of a polymer ~~material containing~~ material, the polymer material comprising:

at least a base ~~polymer~~ polymer; and

at least one thermally-conductive filler material mixed in the at least the base polymer material, and

wherein the thermally-conductive fluid ejector carriage device comprises a receiving area usable to receive a cartridge comprising a container that stores a fluid to be ejected by the fluid ejector module in contact with the fluid ejector module.

2-3. (Canceled)

4. (Previously Presented) The fluid ejector carriage assembly of claim 1, wherein the at least one thermally-conductive filler material has a thermal conductivity greater than about 10 W/m°C.

5. (Previously Presented) The fluid ejector carriage assembly of claim 1, wherein the at least one thermally-conductive filler material has a thermal conductivity less than about 100 W/m°C.

6. (Original) The fluid ejector carriage assembly of claim 5, wherein the at least one thermally-conductive filler material has a thermal conductivity of greater than about 10 W/m°C.

7. (Previously Presented) The fluid ejector carriage assembly of claim 1, wherein the at least one thermally-conductive filler material is a graphite material.

8. (Original) The fluid ejector carriage assembly of claim 7, wherein the graphite material is formed using a petroleum pitch base material.

9. (Previously Presented) The fluid ejector carriage assembly of claim 1, wherein the at least one thermally-conductive filler material is a ceramic material.

10. (Original) The fluid ejector carriage assembly of claim 9, wherein the at least one ceramic material is at least one of boron nitride and aluminum nitride.

11. (Previously Presented) The fluid ejector carriage assembly of claim 1, wherein the base polymer is at least one of liquid crystal polymer, polyphenylene sulfide and polysulfone.

12. (Previously Presented) The fluid ejector carriage assembly of claim 1, wherein the base polymer is chemically resistant to ink.

13. (Original) The fluid ejector carriage assembly of claim 1, wherein the thermally-conductive fluid ejector carriage device and fluid ejector module are made of materials having similar coefficients of thermal expansion.

14. (Original) The fluid ejector carriage assembly of claim 1, wherein the contact between the thermally-conductive fluid ejector carriage device and the fluid ejector module is augmented with at least one compliant, thermally-conductive pad.

15. (Original) The fluid ejector carriage assembly of claim 1, wherein the contact between the thermally-conductive fluid ejector carriage device and the fluid ejector module is augmented with at least one thermally-conductive heat sink compound.

16. (Original) The fluid ejector carriage assembly of claim 1, wherein the contact between the thermally-conductive fluid ejector carriage device and the fluid ejector module comprises at least a temporary bond between the thermally-conductive fluid ejector carriage device and the fluid ejector module.

17. (Original) The fluid ejector carriage assembly of claim 1, wherein the contact between the thermally-conductive fluid ejector carriage device and the fluid ejector module is augmented with at least one mechanical device or structure.

18. (Canceled)

19. (Currently Amended) The fluid ejector carriage assembly of ~~claim 18,~~ claim 1, wherein the container that stores the fluid is molded from a thermally-conductive material and the contact between the container that stores fluid and the fluid ejector module establishes a heat flow path for heat dissipation.

20. (Original) The fluid ejector carriage assembly of claim 19, wherein the contact between the container that stores fluid and the fluid ejector module is augmented with at least one compliant, thermally-conductive pad.

21. (Original) The fluid ejector carriage assembly of claim 19, wherein the contact between the container that stores fluid and the fluid ejector module is augmented with at least one thermally-conductive heat sink compound.

22. (Original) The fluid ejector carriage assembly of claim 19, wherein the contact between the container that stores fluid and the fluid ejector module comprises at least a temporary bond between the container that stores fluid and the fluid ejector module.

23. (Original) The fluid ejector carriage assembly of claim 19, wherein the contact between the container that stores fluid and the fluid ejector module is augmented with at least one mechanical device or structure.

24. (Original) The fluid ejector carriage assembly of claim 1, wherein the thermally-conductive fluid ejector carriage device further comprises multiple receiving areas usable to receive multiple fluid ejector modules.

25. (Original) The fluid ejector carriage assembly of claim 24, wherein each receiving area is usable to receive a cartridge comprising a container that stores a fluid to be ejected by the fluid ejector module in contact with a fluid ejector module.

26. (Original) The fluid ejector carriage assembly of claim 1, wherein the thermally-conductive fluid ejector carriage device further comprises an integral molded heat sink.

27. (Currently Amended) A fluid ejector carriage assembly, comprising:

a thermally-conductive fluid ejector carriage device; and.

a fluid ejector module in thermal contact with the thermally-conductive fluid ejector carriage device,

wherein the thermally-conductive fluid ejector carriage device is molded from a polymer material containing at least a base polymer and at least one thermally-conductive filler material, and the thermally-conductive fluid ejector carriage device comprises a receiving area usable to receive a cartridge comprising a container that stores a fluid to be ejected by the fluid ejector module in contact with the fluid ejector module, ~~The fluid ejector carriage assembly of claim 1, wherein~~ and a separate heat sink is mounted in contact with the thermally-conductive fluid ejector carriage device.

28. (Original) The fluid ejector carriage assembly of claim 27, wherein the contact between the thermally-conductive fluid ejector carriage device and the separately mounted heat sink is augmented with at least one compliant, thermally-conductive pad.

29. (Original) The fluid ejector carriage assembly of claim 27, wherein the contact between the thermally-conductive fluid ejector carriage device and the separately mounted heat sink is augmented with at least one thermally-conductive heat sink compound.

30. (Original) The fluid ejector carriage assembly of claim 27, wherein the contact between the thermally-conductive fluid ejector carriage device and the separately mounted heat sink comprises at least a temporary bond between the thermally-conductive fluid ejector carriage device and the separately mounted heat sink.

31. (Original) The fluid ejector carriage assembly of claim 27, wherein the contact between the thermally-conductive fluid ejector carriage device and the separately mounted heat sink is augmented with at least one mechanical device or structure.

32-36. (Canceled)

37. (Previously Presented) A method for dissipating heat from a thermal fluid ejector module, comprising:

establishing a heat flow path from at least one thermal fluid ejector module through contact with a thermally-conductive polymer carriage device, the thermally-conductive polymer carriage device being molded from a polymer material containing at least a base polymer and at least one thermally-conductive filler material, and the thermally-conductive polymer carriage device being provided with at least one receiving area that is suitably sized to accept at least one integral print cartridge comprising a fluid ejector module assembly and a container that stores a fluid to be ejected by the fluid ejector module;

operating at least one thermal fluid ejector module in contact with the thermally-conductive polymer carriage device in a manner that generates excess heat in the fluid ejector module; and

transferring the excess heat from the at least one thermal fluid ejector module to ambient air surrounding the thermally-conductive polymer carriage device through the heat

flow path established by the contact between the at least one thermal fluid ejector module and the thermally-conductive polymer carriage device.

38. (Original) The method of claim 37, further comprising establishing contact between the thermal fluid ejector module and the thermally-conductive polymer carriage device by force-fitting at least one thermal fluid ejector module into a suitably sized receiving area in the thermally-conductive polymer carriage device so that the fluid ejector module is exposed to a suitable thermally-conductive contact area on an internal face of the receiving area.

39. (Canceled)

40. (Original) The method of claim 38, wherein establishing the contact between the fluid ejector module and the thermally-conductive polymer carriage device further comprises forming at least a temporary bond between the fluid ejector module and the thermally-conductive polymer carriage device.

41. (Original) The method of claim 38, further comprising augmenting the contact between the fluid ejector module and the thermally-conductive polymer carriage device using at least one compliant, thermally-conductive pad.

42. (Original) The method of claim 38, further comprising augmenting the contact between the fluid ejector module and the thermally-conductive polymer carriage device using at least one thermally-conductive heat sink compound.

43. (Original) The method of claim 38, further comprising augmenting the contact between the fluid ejector module and the thermally-conductive polymer carriage device using at least one mechanical device or structure.

44. (Original) The method of claim 37, wherein establishing the heat flow path comprises establishing at least one heat flow path from the thermally-conductive polymer carriage device to at least one heat sink.

45. (Original) The method of claim 44, wherein establishing the at least one heat flow path from the thermally-conductive polymer carriage device to the at least one additional heat sink comprises integrally molding the at least one heat sink with the thermally-conductive polymer carriage device.

46. (Original) The method of claim 44, wherein establishing the at least one heat flow path from the thermally-conductive polymer carriage device to the at least one additional heat sink comprises mounting the at least one heat sink in contact with the thermally-conductive polymer carriage device.

47. (Original) The method of claim 46, wherein establishing the contact between the at least one heat sink and the thermally-conductive polymer carriage device further comprises forming at least a temporary bond between the at least one heat sink and the thermally-conductive polymer carriage device.

48. (Original) The method of claim 46, further comprising augmenting the contact between the at least one heat sink and the thermally-conductive polymer carriage device using at least one compliant, thermally-conductive pad.

49. (Original) The method of claim 46, further comprising augmenting the contact between the at least one heat sink and the thermally-conductive polymer carriage device using at least one thermally-conductive heat sink compound.

50. (Original) The method of claim 46, further comprising augmenting the contact between the at least one heat sink and the thermally-conductive polymer carriage device using at least one mechanical device or structure.